

SSM P/N: CSB01844

THIS METALLIZED AREA IS
CONNECTED TO DIE ATTACH
PAD (PART No.01 ONLY)

.050 R
NOTCH

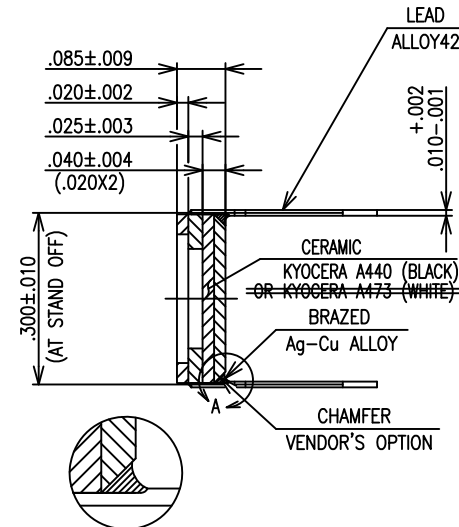
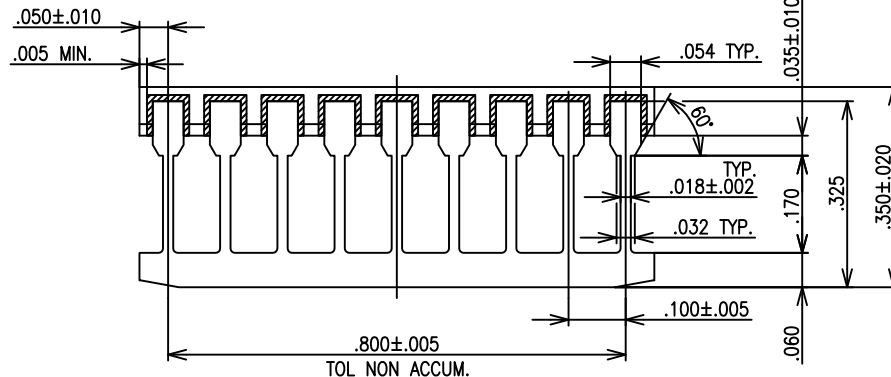
GRAINDING AFTER
Au PLATING.
(ONLY PART No.03)

LEAD No.1 2

INDEX MARK
(SEE TABLE)

THIS METALLIZED SURFACE TO BE
FLAT WITHIN .002 TIR.

PART No.	INDEX MARK	LEAD TIED DOWN	NOTCH AREA METALLIZED
01	⊗	NIL	WITH METALLIZATION
02	⊕	NO.1 ONLY	WITH METALLIZATION
03	⊗	NIL	WITHOUT METALLIZATION



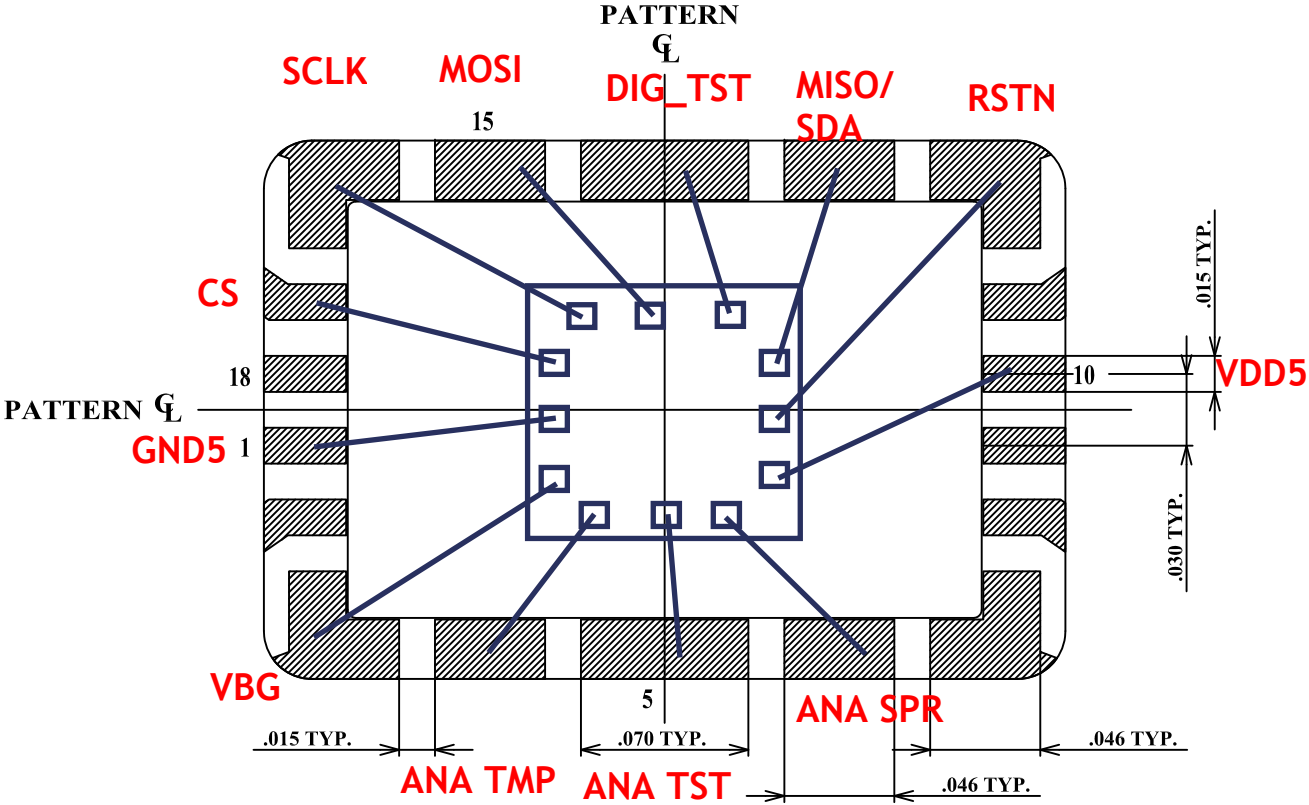
DETAIL-A

NOTES



1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
2. SEAL AREA TO BE METALLIZED.
3. DIE ATTACH AREA TO BE METALLIZED.
4. SEAL RING TO BE FLOATING FROM ANY LEADS.
5. LEAD RESISTANCE : 0.10 OHM MAX. AT LEAD NO.9,18 OTHER LESS THAN 0.20 OHM MAX.
6. WIRE BOND PAD CONNECTED TO CORRESPONDED OUTER LEADS.
7. MISALIGNMENT OF METALLIZATION PATTERN IN CAVITY SHALL BE ACCEPTED DUE TO LAYER MISALIGNMENT.

SB018H032-3	S=0 D=0
SB018H032-2	S=0 D=1
SB018H032-1	S=0 D=0

MODIFICATION							NAME 18 LEAD SIDE BRAZED PACKAGE		TOLERANCE UNLESS OTHERWISE SPECIFIED ±.005 THIRD ANGLE PROJECTION	DRAWN M.K	CHECKED K.M	APPROVED	DATE FEB.18.'7
							SCALE 5 / 1	MATERIAL AS INDICATED					
	A	REDRAWN : (DELETE PART No.02 , ADDED PART No.03)		MAR.18.'10	T.M/Y.H	H.TA/S.NI	Y.F						
	G	REDRAWN: (CONVERTED CAD DATA) ADDED:SHEET 2/2		OCT.20.'94	K.I	T.C/S.F	T.A						
		CHANGED		DATE	DRAWN	CHECKED	APPROVED	KYOCERA	KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO. KD-S77032-H			SHEET 1/2



BONDING PATTERN

MODIFICATION						NAME	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
						18 LEAD SIDE BRAZED PACKAGE	UNLESS OTHERWISE SPECIFIED	M.K	K.M		FEB.18.77
						SCALE20 / 1	MATERIAL				
							THIRD ANGLE PROJECTION				
		REDRAWN: (CONVERTED CAD DATA)	OCT.20.94	K.I	T.C.S.F	T.A		KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO.		
CHANGED		DATE	DRAWN	CHECKED	APPROVED	KD-S77032-H			2 / 2		

Pins Associated with Layout to Help with Visual Alignment

